



Manufacturing Capabilities

Capability		Standard Production	Advanced Capability
Maximum Production Panel Size	Typical:-	610 x 457 mm	610 x 533 mm
Board Thickness	Typical:- Scored:-	0.25 mm to 5.50 mm 0.30 mm to 3.2 mm	0.10 mm to 5.50 mm 0.30 mm to 3.2 mm
Aspect Ratio	Typical Through Hole:- Typical Blind Hole:-	10 : 1 1 : 1	16 : 1* 1.2 : 1
Multilayer	Maximum:-	24 layers	48 layers **
Core Thickness	Minimum:- Maximum:-	0.05 mm* 2.40 mm	0.05 mm * 5.5 mm
Copper Thickness	Inner:- Outer:-	18 µm 35 µm 50µm 12 µm 18 µm 35 µm 70 µm 105 µm	Other thicknesses available on request
Copper Plating	Minimum:- Maximum:-	25 µm 50 µm	25 µm 210 µm
Conductor Width / Spacing	Minimum:-	0.075 mm / 0.075 mm	0.050 mm / 0.050 mm
Annular Ring	Inner Layer:- Outer Layer:-	From 0.075 mm (Minimum above finished hole size) From 0.075 mm (Minimum above finished hole size)	From 0.050 mm From 0.050 mm
Inner Layer Clearances	Typical Minimum Clearance:- Typical Minimum Clearance:-	0.30 mm (from copper plane to non-plated hole) 0.30 mm (from copper plane to copper-plated hole)	- -
Special Features	Typical Minimum Clearance:- Typical Minimum Clearance:- Typical Minimum Hole Ø:-	0.25 mm (from copper plane to circuit profile) 0.50 mm (from copper plane to score centre line) 0.10 mm	0.20 mm (from copper plane to circuit profile) 0.30 mm (from copper plane to score centre line) 0.075 mm (for blind vias only)
Ink	To Form Trace Patterns:-	Silver	Carbon

* Smallest finished hole size 0.05mm and aspect ratio of 16:1 available from offshore partners

** 48 layers and minimum core thickness 0.05mm available from offshore partners